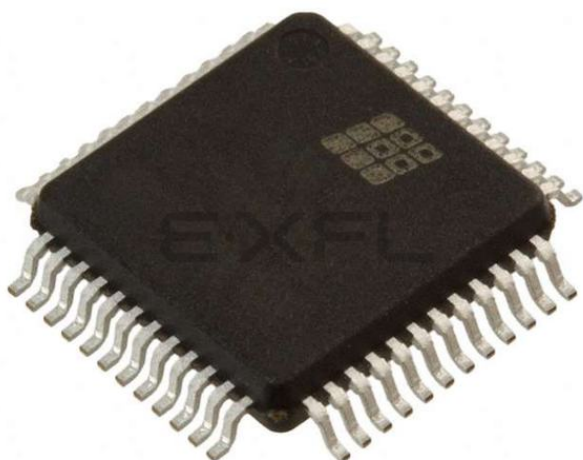




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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	1.65V ~ 1.95V
Number of Logic Elements/Blocks	2
Number of Macrocells	32
Number of Gates	-
Number of I/O	32
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4032c-5t48c

Figure 3. AND Array

Enhanced Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in product term clusters. Each product term cluster is associated with a macrocell. The cluster size for the ispMACH 4000 family is 4+1 (total 5) product terms. The software automatically considers the availability and distribution of product term clusters as it fits the functions within a GLB. The logic allocator is designed to provide three speed paths: 5-PT fast bypass path, 20-PT Speed Locking path and an up to 80-PT path. The availability of these three paths lets designers trade timing variability for increased performance.

The enhanced Logic Allocator of the ispMACH 4000 family consists of the following blocks:

- Product Term Allocator
- Cluster Allocator
- Wide Steering Logic

Figure 4 shows a macrocell slice of the Logic Allocator. There are 16 such slices in the GLB.

Figure 4. Macrocell Slice

Output Routing Pool (ORP)

The Output Routing Pool allows macrocell outputs to be connected to any of several I/O cells within an I/O block. This provides greater flexibility in determining the pinout and allows design changes to occur without affecting the pinout. The output routing pool also provides a parallel capability for routing macrocell-level OE product terms. This allows the OE product term to follow the macrocell output as it is switched between I/O cells. Additionally, the output routing pool allows the macrocell output or true and complement forms of the 5-PT bypass signal to bypass the output routing multiplexers and feed the I/O cell directly. The enhanced ORP of the ispMACH 4000 family consists of the following elements:

- Output Routing Multiplexers
- OE Routing Multiplexers
- Output Routing Pool Bypass Multiplexers

Figure 7 shows the structure of the ORP from the I/O cell perspective. This is referred to as an ORP slice. Each ORP has as many ORP slices as there are I/O cells in the corresponding I/O block.

Figure 7. ORP Slice



Output Routing Multiplexers

The details of connections between the macrocells and the I/O cells vary across devices and within a device dependent on the maximum number of I/Os available. Tables 5-9 provide the connection details.

Table 6. ORP Combinations for I/O Blocks with 8 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5

Table 7. ORP Combinations for I/O Blocks with 16 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M1, M2, M3, M4, M5, M6, M7, M8
I/O 2	M2, M3, M4, M5, M6, M7, M8, M9
I/O 3	M3, M4, M5, M6, M7, M8, M9, M10
I/O 4	M4, M5, M6, M7, M8, M9, M10, M11
I/O 5	M5, M6, M7, M8, M9, M10, M11, M12
I/O 6	M6, M7, M8, M9, M10, M11, M12, M13
I/O 7	M7, M8, M9, M10, M11, M12, M13, M14
I/O 8	M8, M9, M10, M11, M12, M13, M14, M15
I/O 9	M9, M10, M11, M12, M13, M14, M15, M0
I/O 10	M10, M11, M12, M13, M14, M15, M0, M1
I/O 11	M11, M12, M13, M14, M15, M0, M1, M2
I/O 12	M12, M13, M14, M15, M0, M1, M2, M3
I/O 13	M13, M14, M15, M0, M1, M2, M3, M4
I/O 14	M14, M15, M0, M1, M2, M3, M4, M5
I/O 15	M15, M0, M1, M2, M3, M4, M5, M6

Table 8. ORP Combinations for I/O Blocks with 4 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M4, M5, M6, M7, M8, M9, M10, M11
I/O 2	M8, M9, M10, M11, M12, M13, M14, M15
I/O 3	M12, M13, M14, M15, M0, M1, M2, M3

Table 9. ORP Combinations for I/O Blocks with 10 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5
I/O 8	M2, M3, M4, M5, M6, M7, M8, M9
I/O 9	M10, M11, M12, M13, M14, M15, M0, M1

Supply Current, ispMACH 4000V/B/C (Cont.)

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{CC}^{4}	Standby Power Supply Current	$V_{CC} = 3.3V$	—	13	—	mA
		$V_{CC} = 2.5V$	—	13	—	mA
		$V_{CC} = 1.8V$	—	3	—	mA

1. $T_A = 25^{\circ}C$, frequency = 1.0 MHz.
2. Device configured with 16-bit counters.
3. I_{CC} varies with specific device configuration and operating frequency.
4. $T_A = 25^{\circ}C$

Supply Current, ispMACH 4000Z

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4032ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	50	—	μA
		Vcc = 1.9V, T _A = 70°C	—	58	—	μA
		Vcc = 1.9V, T _A = 85°C	—	60	—	μA
		Vcc = 1.9V, T _A = 125°C	—	70	—	μA
ICC ^{4, 5}	Standby Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	10	—	μA
		Vcc = 1.9V, T _A = 70°C	—	13	20	μA
		Vcc = 1.9V, T _A = 85°C	—	15	25	μA
		Vcc = 1.9V, T _A = 125°C	—	22	—	μA
ispMACH 4064ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	80	—	μA
		Vcc = 1.9V, T _A = 70°C	—	89	—	μA
		Vcc = 1.9V, T _A = 85°C	—	92	—	μA
		Vcc = 1.9V, T _A = 125°C	—	109	—	μA
ICC ^{4, 5}	Standby Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	11	—	μA
		Vcc = 1.9V, T _A = 70°C	—	15	25	μA
		Vcc = 1.9V, T _A = 85°C	—	18	35	μA
		Vcc = 1.9V, T _A = 125°C	—	37	—	μA
ispMACH 4128ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	168	—	μA
		Vcc = 1.9V, T _A = 70°C	—	190	—	μA
		Vcc = 1.9V, T _A = 85°C	—	195	—	μA
		Vcc = 1.9V, T _A = 125°C	—	212	—	μA
ICC ^{4, 5}	Standby Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	12	—	μA
		Vcc = 1.9V, T _A = 70°C	—	16	35	μA
		Vcc = 1.9V, T _A = 85°C	—	19	50	μA
		Vcc = 1.9V, T _A = 125°C	—	42	—	μA

I/O DC Electrical Characteristics

Over Recommended Operating Conditions

Standard	V_{IL}		V_{IH}		V_{OL} Max (V)	V_{OH} Min (V)	I_{OL}^1 (mA)	I_{OH}^1 (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LVTTTL	-0.3	0.80	2.0	5.5	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 3.3	-0.3	0.80	2.0	5.5	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 2.5	-0.3	0.70	1.70	3.6	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 1.8 (4000V/B)	-0.3	0.63	1.17	3.6	0.40	$V_{CCO} - 0.45$	2.0	-2.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 1.8 (4000C/Z)	-0.3	$0.35 * V_{CC}$	$0.65 * V_{CC}$	3.6	0.40	$V_{CCO} - 0.45$	2.0	-2.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
PCI 3.3 (4000V/B)	-0.3	1.08	1.5	5.5	$0.1 V_{CCO}$	$0.9 V_{CCO}$	1.5	-0.5
PCI 3.3 (4000C/Z)	-0.3	$0.3 * 3.3 * (V_{CC} / 1.8)$	$0.5 * 3.3 * (V_{CC} / 1.8)$	5.5	$0.1 V_{CCO}$	$0.9 V_{CCO}$	1.5	-0.5

1. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed $n * 8\text{mA}$. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

ispMACH 4000V/B/C Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{GPTOE}	Global PT OE Delay	—	5.58	—	5.58	—	5.78	ns
t _{PTOE}	Macrocell PT OE Delay	—	3.58	—	4.28	—	4.28	ns

Timing v.3.2

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the Timing Model in this data sheet for further details.

ispMACH 4000Z Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{GPTOE}	Global PT OE Delay	—	1.9	—	2.35	—	2.60	ns
t _{PPTOE}	Macrocell PT OE Delay	—	2.4	—	3.35	—	2.60	ns

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the timing model in this data sheet for further details.

Timing v.2.2

ispMACH 4000Z Internal Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t _{IN}	Input Buffer Delay	—	0.95	—	1.25	—	1.80	ns
t _{GOE}	Global OE Pin Delay	—	3.00	—	3.50	—	4.30	ns
t _{GCLK_IN}	Global Clock Input Buffer Delay	—	1.95	—	2.05	—	2.15	ns
t _{BUF}	Delay through Output Buffer	—	1.10	—	1.00	—	1.30	ns
t _{EN}	Output Enable Time	—	2.50	—	2.50	—	2.70	ns
t _{DIS}	Output Disable Time	—	2.50	—	2.50	—	2.70	ns
Routing/GLB Delays								
t _{ROUTE}	Delay through GRP	—	2.25	—	2.05	—	2.50	ns
t _{MCELL}	Macrocell Delay	—	0.65	—	0.65	—	1.00	ns
t _{INREG}	Input Buffer to Macrocell Register Delay	—	1.00	—	1.00	—	1.00	ns
t _{FBK}	Internal Feedback Delay	—	0.35	—	0.05	—	0.05	ns
t _{PDb}	5-PT Bypass Propagation Delay	—	0.20	—	0.70	—	1.90	ns
t _{PDi}	Macrocell Propagation Delay	—	0.45	—	0.65	—	1.00	ns
Register/Latch Delays								
t _S	D-Register Setup Time (Global Clock)	1.00	—	1.10	—	1.35	—	ns
t _{S_PT}	D-Register Setup Time (Product Term Clock)	2.10	—	1.90	—	2.45	—	ns
t _{ST}	T-Register Setup Time (Global Clock)	1.20	—	1.30	—	1.55	—	ns
t _{ST_PT}	T-register Setup Time (Product Term Clock)	2.30	—	2.10	—	2.75	—	ns
t _H	D-Register Hold Time	1.90	—	1.90	—	3.15	—	ns
t _{HT}	T-Resister Hold Time	1.90	—	1.90	—	3.15	—	ns
t _{SIR}	D-Input Register Setup Time (Global Clock)	1.30	—	1.10	—	0.75	—	ns
t _{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t _{HIR}	D-Input Register Hold Time (Global Clock)	1.30	—	1.50	—	1.95	—	ns
t _{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	1.00	—	1.00	—	1.18	—	ns
t _{COi}	Register Clock to Output/Feedback MUX Time	—	0.75	—	1.15	—	1.05	ns
t _{CES}	Clock Enable Setup Time	2.00	—	2.00	—	2.00	—	ns
t _{CEH}	Clock Enable Hold Time	0.00	—	0.00	—	0.00	—	ns
t _{SL}	Latch Setup Time (Global Clock)	1.00	—	1.00	—	1.65	—	ns
t _{SL_PT}	Latch Setup Time (Product Term Clock)	2.10	—	1.90	—	2.15	—	ns
t _{HL}	Latch Hold Time	2.00	—	2.00	—	1.17	—	ns
t _{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	ns
t _{PDLi}	Propagation Delay through Transparent Latch to Output/ Feedback MUX	—	0.25	—	0.25	—	0.25	ns
t _{SRi}	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.97	—	0.97	—	0.28	ns
t _{SRR}	Asynchronous Reset or Set Recovery Delay	—	1.80	—	1.80	—	1.67	ns
Control Delays								
t _{BCLK}	GLB PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
t _{PTCLK}	Macrocell PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
t _{BSR}	GLB PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	ns
t _{PTSR}	Macrocell PT Set/Reset Delay	—	1.83	—	1.83	—	2.72	ns
t _{GPTOE}	Global PT OE Delay	—	4.30	—	4.20	—	3.50	ns

Signal Descriptions

Signal Names	Description
TMS	Input – This pin is the IEEE 1149.1 Test Mode Select input, which is used to control the state machine.
TCK	Input – This pin is the IEEE 1149.1 Test Clock input pin, used to clock through the state machine.
TDI	Input – This pin is the IEEE 1149.1 Test Data In pin, used to load data.
TDO	Output – This pin is the IEEE 1149.1 Test Data Out pin used to shift data out.
GOE0/IO, GOE1/IO	These pins are configured to be either Global Output Enable Input or as general I/O pins.
GND	Ground
NC	Not Connected
V _{CC}	The power supply pins for logic core and JTAG port.
CLK0/I, CLK1/I, CLK2/I, CLK3/I	These pins are configured to be either CLK input or as an input.
V _{CC00} , V _{CC01}	The power supply pins for each I/O bank.
yzz	Input/Output ¹ – These are the general purpose I/O used by the logic array. y is GLB reference (alpha) and z is macrocell reference (numeric). z: 0-15.
	ispMACH 4032 y: A-B
	ispMACH 4064 y: A-D
	ispMACH 4128 y: A-H
	ispMACH 4256 y: A-P
	ispMACH 4384 y: A-P, AX-HX
	ispMACH 4512 y: A-P, AX-PX

1. In some packages, certain I/Os are only available for use as inputs. See the signal connections table for details.

ispMACH 4000V/B/C ORP Reference Table

	4032V/B/C		4064V/B/C			4128V/B/C			4256V/B/C				4384V/B/C		4512V/B/C	
Number of I/Os	30 ¹	32	30 ²	32	64	64	92 ³	96	64	96 ⁴	128	160	128	192	128	208
Number of GLBs	2	2	4	4	4	8	8	8	16	16	16	16	16	16	16	16
Number of I/Os / GLB	16	16	8	8	16	8	12	12	4	8	8	10	8	8	8	Mixture of 8 & 4 ⁵
Reference ORP Table	16 I/Os / GLB		8 I/Os / GLB		16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB		4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB	10 I/Os / GLB	8 I/Os / GLB		8 I/Os / GLB	8 I/Os / GLB 4 I/Os / GLB

1. 32-macrocell device, 44 TQFP: 2 GLBs have 15 out of 16 I/Os bonded out.

2. 64-macrocells device, 44 TQFP: 2 GLBs have 7 out of 8 I/Os bonded out.

3. 128-macrocell device, 128 TQFP: 4 GLBs have 11 out of 12 I/Os

4. 256-macrocell device, 144 TQFP: 16 GLBs have 6 I/Os per

5. 512-macrocell device: 20 GLBs have 8 I/Os per, 12 GLBs have 4 I/Os per

ispMACH 4000Z ORP Reference Table

	4032Z	4064Z		4128Z		4256Z		
Number of I/Os	32	32	64	64	96	64	96 ¹	128
Number of GLBs	2	4	4	8	8	16	16	16
Number of I/Os / GLB	16	8	16	8	12	4	8	8
Reference ORP Table	16 I/Os / GLB	8 I/Os / GLB	16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB	4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB

1. 256-macrocell device, 132 csBGA: 16 GLBs have 6 I/Os per

ispMACH 4000V/B/C/Z Power Supply and NC Connections¹

Signal	44-pin TQFP ²	48-pin TQFP ²	56-ball csBGA ³	100-pin TQFP ²	128-pin TQFP ²
VCC	11, 33	12, 36	K2, A9	25, 40, 75, 90	32, 51, 96, 115
VCCO0 VCCO (Bank 0)	6	6	F3	13, 33, 95	3, 17, 30, 41, 122
VCCO1 VCCO (Bank 1)	28	30	E8	45, 63, 83	58, 67, 81, 94, 105
GND	12, 34	13, 37	H3, C8	1, 26, 51, 76	1, 33, 65, 97
GND (Bank 0)	5	5	D3	7, 18, 32, 96	10, 24, 40, 113, 123
GND (Bank 1)	27	29	G8	46, 57, 68, 82	49, 59, 74, 88, 104
NC	—	—	4032Z: A8, B10, E1, E3, F8, F10, J1, K3	—	—

1. All grounds must be electrically connected at the board level. However, for the purposes of I/O current loading, grounds are associated with the bank shown.
2. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.
3. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.

**ispMACH 4064V/B/C/Z, 4128V/B/C/Z, 4256V/B/C/Z Logic Signal Connections:
100-Pin TQFP**

Pin Number	Bank Number	ispMACH 4064V/B/C/Z		ispMACH 4128V/B/C/Z		ispMACH 4256V/B/C/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	GND	-	GND	-	GND	-
2	-	TDI	-	TDI	-	TDI	-
3	0	A8	A^8	B0	B^0	C12	C^3
4	0	A9	A^9	B2	B^1	C10	C^2
5	0	A10	A^10	B4	B^2	C6	C^1
6	0	A11	A^11	B6	B^3	C2	C^0
7	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
8	0	A12	A^12	B8	B^4	D12	D^3
9	0	A13	A^13	B10	B^5	D10	D^2
10	0	A14	A^14	B12	B^6	D6	D^1
11	0	A15	A^15	B13	B^7	D4	D^0
12*	0	I	-	I	-	I	-
13	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
14	0	B15	B^15	C14	C^7	E4	E^0
15	0	B14	B^14	C12	C^6	E6	E^1
16	0	B13	B^13	C10	C^5	E10	E^2
17	0	B12	B^12	C8	C^4	E12	E^3
18	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
19	0	B11	B^11	C6	C^3	F2	F^0
20	0	B10	B^10	C5	C^2	F6	F^1
21	0	B9	B^9	C4	C^1	F10	F^2
22	0	B8	B^8	C2	C^0	F12	F^3
23*	0	I	-	I	-	I	-
24	-	TCK	-	TCK	-	TCK	-
25	-	VCC	-	VCC	-	VCC	-
26	-	GND	-	GND	-	GND	-
27*	0	I	-	I	-	I	-
28	0	B7	B^7	D13	D^7	G12	G^3
29	0	B6	B^6	D12	D^6	G10	G^2
30	0	B5	B^5	D10	D^5	G6	G^1
31	0	B4	B^4	D8	D^4	G2	G^0
32	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
33	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
34	0	B3	B^3	D6	D^3	H12	H^3
35	0	B2	B^2	D4	D^2	H10	H^2
36	0	B1	B^1	D2	D^1	H6	H^1
37	0	B0	B^0	D0	D^0	H2	H^0
38	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
39	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
40	-	VCC	-	VCC	-	VCC	-
41	1	C0	C^0	E0	E^0	I2	I^0

**ispMACH 4064V/B/C/Z, 4128V/B/C/Z, 4256V/B/C/Z Logic Signal Connections:
100-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4064V/B/C/Z		ispMACH 4128V/B/C/Z		ispMACH 4256V/B/C/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
42	1	C1	C ¹	E2	E ¹	I6	I ¹
43	1	C2	C ²	E4	E ²	I10	I ²
44	1	C3	C ³	E6	E ³	I12	I ³
45	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
46	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
47	1	C4	C ⁴	E8	E ⁴	J2	J ⁰
48	1	C5	C ⁵	E10	E ⁵	J6	J ¹
49	1	C6	C ⁶	E12	E ⁶	J10	J ²
50	1	C7	C ⁷	E14	E ⁷	J12	J ³
51	-	GND	-	GND	-	GND	-
52	-	TMS	-	TMS	-	TMS	-
53	1	C8	C ⁸	F0	F ⁰	K12	K ³
54	1	C9	C ⁹	F2	F ¹	K10	K ²
55	1	C10	C ¹⁰	F4	F ²	K6	K ¹
56	1	C11	C ¹¹	F6	F ³	K2	K ⁰
57	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
58	1	C12	C ¹²	F8	F ⁴	L12	L ³
59	1	C13	C ¹³	F10	F ⁵	L10	L ²
60	1	C14	C ¹⁴	F12	F ⁶	L6	L ¹
61	1	C15	C ¹⁵	F13	F ⁷	L4	L ⁰
62*	1	I	-	I	-	I	-
63	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
64	1	D15	D ¹⁵	G14	G ⁷	M4	M ⁰
65	1	D14	D ¹⁴	G12	G ⁶	M6	M ¹
66	1	D13	D ¹³	G10	G ⁵	M10	M ²
67	1	D12	D ¹²	G8	G ⁴	M12	M ³
68	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
69	1	D11	D ¹¹	G6	G ³	N2	N ⁰
70	1	D10	D ¹⁰	G5	G ²	N6	N ¹
71	1	D9	D ⁹	G4	G ¹	N10	N ²
72	1	D8	D ⁸	G2	G ⁰	N12	N ³
73*	1	I	-	I	-	I	-
74	-	TDO	-	TDO	-	TDO	-
75	-	VCC	-	VCC	-	VCC	-
76	-	GND	-	GND	-	GND	-
77*	1	I	-	I	-	I	-
78	1	D7	D ⁷	H13	H ⁷	O12	O ³
79	1	D6	D ⁶	H12	H ⁶	O10	O ²
80	1	D5	D ⁵	H10	H ⁵	O6	O ¹
81	1	D4	D ⁴	H8	H ⁴	O2	O ⁰
82	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:
132-Ball csBGA (Cont.)**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
P8	1	NC ¹	-	NC ¹	-	I ¹	-
M8	1	NC	-	E0	E ⁰	I2	I ¹
P9	1	C0	C ⁰	E1	E ¹	I4	I ²
N9	1	C1	C ¹	E2	E ²	I6	I ³
M9	1	C2	C ²	E4	E ³	I8	I ⁴
N10	1	C3	C ³	E5	E ⁴	I10	I ⁵
P10	1	NC	-	E6	E ⁵	I12	I ⁶
M10	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
N11	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
P11	1	NC	-	E8	E ⁶	J2	J ¹
M11	1	C4	C ⁴	E9	E ⁷	J4	J ²
P12	1	C5	C ⁵	E10	E ⁸	J6	J ³
N12	1	C6	C ⁶	E12	E ⁹	J8	J ⁴
P13	1	C7	C ⁷	E13	E ¹⁰	J10	J ⁵
P14	1	NC	-	E14	E ¹¹	J12	J ⁶
N14	-	GND	-	GND	-	GND	-
N13	-	TMS	-	TMS	-	TMS	-
M14	1	NC	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
M12	1	NC	-	F0	F ⁰	K12	K ⁶
M13	1	C8	C ⁸	F1	F ¹	K10	K ⁵
L14	1	C9	C ⁹	F2	F ²	K8	K ⁴
L12	1	C10	C ¹⁰	F4	F ³	K6	K ³
L13	1	C11	C ¹¹	F5	F ⁴	K4	K ²
K14	1	NC	-	F6	F ⁵	K2	K ¹
K13	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
K12	1	NC	-	F8	F ⁶	L12	L ⁶
J13	1	C12	C ¹²	F9	F ⁷	L10	L ⁵
J14	1	C13	C ¹³	F10	F ⁸	L8	L ⁴
J12	1	C14	C ¹⁴	F12	F ⁹	L6	L ³
H14	1	C15	C ¹⁵	F13	F ¹⁰	L4	L ²
H13	1	I	-	F14	F ¹¹	L2	L ¹
H12	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
G13	1	NC	-	G14	G ¹¹	M2	M ¹
G14	1	NC	-	G13	G ¹⁰	M4	M ²
G12	1	D15	D ¹⁵	G12	G ⁹	M6	M ³
F14	1	D14	D ¹⁴	G10	G ⁸	M8	M ⁴
F13	1	D13	D ¹³	G9	G ⁷	M10	M ⁵
F12	1	D12	D ¹²	G8	G ⁶	M12	M ⁶
E13	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
E14	1	NC	-	G6	G ⁵	N2	N ¹
E12	1	D11	D ¹¹	G5	G ⁴	N4	N ²

ispMACH 4128V and 4256V Logic Signal Connections: 144-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V		ispMACH 4256V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
129	-	VCC	-	VCC	-
130	0	A0/GOE0	A^0	A2/GOE0	A^1
131	0	A1	A^1	A4	A^2
132	0	A2	A^2	A6	A^3
133	0	A4	A^3	A8	A^4
134	0	A5	A^4	A10	A^5
135	0	A6	A^5	A12	A^6
136	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
137	0	GND (Bank 0)	-	GND (Bank 0)	-
138	0	A8	A^6	B2	B^1
139	0	A9	A^7	B4	B^2
140	0	A10	A^8	B6	B^3
141	0	A12	A^9	B8	B^4
142	0	A13	A^10	B10	B^5
143	0	A14	A^11	B12	B^6
144	0	NC ²	-	I ²	-

1. For device migration considerations, these NC pins are GND pins for I/O banks in ispMACH 4128V devices.

2. For device migration considerations, these NC pins are input signal pins in ispMACH 4256V devices.

ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections: 176-Pin TQFP

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	NC	-	NC	-	NC	-
2	-	GND	-	GND	-	GND	-
3	-	TDI	-	TDI	-	TDI	-
4	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
5	0	C14	C^7	C14	C^7	C14	C^7
6	0	C12	C^6	C12	C^6	C12	C^6
7	0	C10	C^5	C10	C^5	C10	C^5
8	0	C8	C^4	C8	C^4	C8	C^4
9	0	C6	C^3	C6	C^3	C6	C^3
10	0	C4	C^2	C4	C^2	C4	C^2
11	0	C2	C^1	C2	C^1	C2	C^1
12	0	C0	C^0	C0	C^0	C0	C^0
13	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
14	0	D14	D^7	E14	E^7	G14	G^7
15	0	D12	D^6	E12	E^6	G12	G^6
16	0	D10	D^5	E10	E^5	G10	G^5
17	0	D8	D^4	E8	E^4	G8	G^4
18	0	D6	D^3	E6	E^3	G6	G^3

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
60	0	H8	H ⁴	L8	L ⁴	P8	P ⁴
61	0	H6	H ³	L6	L ³	P6	P ³
62	0	H4	H ²	L4	L ²	P4	P ²
63	0	H2	H ¹	L2	L ¹	P2	P ¹
64	0	H0	H ⁰	L0	L ⁰	P0	P ⁰
65	-	GND	-	GND	-	GND	-
66	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
67	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
68	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
69	-	VCC	-	VCC	-	VCC	-
70	1	I0	I ⁰	M0	M ⁰	AX0	AX ⁰
71	1	I2	I ¹	M2	M ¹	AX2	AX ¹
72	1	I4	I ²	M4	M ²	AX4	AX ²
73	1	I6	I ³	M6	M ³	AX6	AX ³
74	1	I8	I ⁴	M8	M ⁴	AX8	AX ⁴
75	1	I10	I ⁵	M10	M ⁵	AX10	AX ⁵
76	1	I12	I ⁶	M12	M ⁶	AX12	AX ⁶
77	1	I14	I ⁷	M14	M ⁷	AX14	AX ⁷
78	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
79	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
80	1	J0	J ⁰	N0	N ⁰	BX0	BX ⁰
81	1	J2	J ¹	N2	N ¹	BX2	BX ¹
82	1	J4	J ²	N4	N ²	BX4	BX ²
83	1	J6	J ³	N6	N ³	BX6	BX ³
84	1	J8	J ⁴	N8	N ⁴	BX8	BX ⁴
85	1	J10	J ⁵	N10	N ⁵	BX10	BX ⁵
86	1	J12	J ⁶	N12	N ⁶	BX12	BX ⁶
87	1	J14	J ⁷	N14	N ⁷	BX14	BX ⁷
88	-	VCC	-	VCC	-	VCC	-
89	-	NC	-	NC	-	NC	-
90	-	GND	-	GND	-	GND	-
91	-	TMS	-	TMS	-	TMS	-
92	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
93	1	K14	K ⁷	O14	O ⁷	CX14	CX ⁷
94	1	K12	K ⁶	O12	O ⁶	CX12	CX ⁶
95	1	K10	K ⁵	O10	O ⁵	CX10	CX ⁵
96	1	K8	K ⁴	O8	O ⁴	CX8	CX ⁴
97	1	K6	K ³	O6	O ³	CX6	CX ³
98	1	K4	K ²	O4	O ²	CX4	CX ²
99	1	K2	K ¹	O2	O ¹	CX2	CX ¹
100	1	K0	K ⁰	O0	O ⁰	CX0	CX ⁰

ispMACH 4000C (1.8V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-5T48I	32	1.8	5	TQFP	48	32	I
	LC4032C-75T48I	32	1.8	7.5	TQFP	48	32	I
	LC4032C-10T48I	32	1.8	10	TQFP	48	32	I
	LC4032C-5T44I	32	1.8	5	TQFP	44	30	I
	LC4032C-75T44I	32	1.8	7.5	TQFP	44	30	I
	LC4032C-10T44I	32	1.8	10	TQFP	44	30	I
LC4064C	LC4064C-5T100I	64	1.8	5	TQFP	100	64	I
	LC4064C-75T100I	64	1.8	7.5	TQFP	100	64	I
	LC4064C-10T100I	64	1.8	10	TQFP	100	64	I
	LC4064C-5T48I	64	1.8	5	TQFP	48	32	I
	LC4064C-75T48I	64	1.8	7.5	TQFP	48	32	I
	LC4064C-10T48I	64	1.8	10	TQFP	48	32	I
	LC4064C-5T44I	64	1.8	5	TQFP	44	30	I
	LC4064C-75T44I	64	1.8	7.5	TQFP	44	30	I
	LC4064C-10T44I	64	1.8	10	TQFP	44	30	I
LC4128C	LC4128C-5T128I	128	1.8	5	TQFP	128	92	I
	LC4128C-75T128I	128	1.8	7.5	TQFP	128	92	I
	LC4128C-10T128I	128	1.8	10	TQFP	128	92	I
	LC4128C-5T100I	128	1.8	5	TQFP	100	64	I
	LC4128C-75T100I	128	1.8	7.5	TQFP	100	64	I
	LC4128C-10T100I	128	1.8	10	TQFP	100	64	I
LC4256C	LC4256C-5FT256AI	256	1.8	5	ftBGA	256	128	I
	LC4256C-75FT256AI	256	1.8	7.5	ftBGA	256	128	I
	LC4256C-10FT256AI	256	1.8	10	ftBGA	256	128	I
	LC4256C-5FT256BI	256	1.8	5	ftBGA	256	160	I
	LC4256C-75FT256BI	256	1.8	7.5	ftBGA	256	160	I
	LC4256C-10FT256BI	256	1.8	10	ftBGA	256	160	I
	LC4256C-5F256AI ¹	256	1.8	5	fpBGA	256	128	I
	LC4256C-75F256AI ¹	256	1.8	7.5	fpBGA	256	128	I
	LC4256C-10F256AI ¹	256	1.8	10	fpBGA	256	128	I
	LC4256C-5F256BI ¹	256	1.8	5	fpBGA	256	160	I
	LC4256C-75F256BI ¹	256	1.8	7.5	fpBGA	256	160	I
	LC4256C-10F256BI ¹	256	1.8	10	fpBGA	256	160	I
	LC4256C-5T176I	256	1.8	5	TQFP	176	128	I
	LC4256C-75T176I	256	1.8	7.5	TQFP	176	128	I
	LC4256C-10T176I	256	1.8	10	TQFP	176	128	I
	LC4256C-5T100I	256	1.8	5	TQFP	100	64	I
	LC4256C-75T100I	256	1.8	7.5	TQFP	100	64	I
	LC4256C-10T100I	256	1.8	10	TQFP	100	64	I

ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4128V	LC4128V-27T144C	128	3.3	2.7	TQFP	144	96	C
	LC4128V-5T144C	128	3.3	5	TQFP	144	96	C
	LC4128V-75T144C	128	3.3	7.5	TQFP	144	96	C
	LC4128V-27T128C	128	3.3	2.7	TQFP	128	92	C
	LC4128V-5T128C	128	3.3	5	TQFP	128	92	C
	LC4128V-75T128C	128	3.3	7.5	TQFP	128	92	C
	LC4128V-27T100C	128	3.3	2.7	TQFP	100	64	C
	LC4128V-5T100C	128	3.3	5	TQFP	100	64	C
	LC4128V-75T100C	128	3.3	7.5	TQFP	100	64	C
LC4256V	LC4256V-3FT256AC	256	3.3	3	ftBGA	256	128	C
	LC4256V-5FT256AC	256	3.3	5	ftBGA	256	128	C
	LC4256V-75FT256AC	256	3.3	7.5	ftBGA	256	128	C
	LC4256V-3FT256BC	256	3.3	3	ftBGA	256	160	C
	LC4256V-5FT256BC	256	3.3	5	ftBGA	256	160	C
	LC4256V-75FT256BC	256	3.3	7.5	ftBGA	256	160	C
	LC4256V-3F256AC ¹	256	3.3	3	fpBGA	256	128	C
	LC4256V-5F256AC ¹	256	3.3	5	fpBGA	256	128	C
	LC4256V-75F256AC ¹	256	3.3	7.5	fpBGA	256	128	C
	LC4256V-3F256BC ¹	256	3.3	3	fpBGA	256	160	C
	LC4256V-5F256BC ¹	256	3.3	5	fpBGA	256	160	C
	LC4256V-75F256BC ¹	256	3.3	7.5	fpBGA	256	160	C
	LC4256V-3T176C	256	3.3	3	TQFP	176	128	C
	LC4256V-5T176C	256	3.3	5	TQFP	176	128	C
	LC4256V-75T176C	256	3.3	7.5	TQFP	176	128	C
	LC4256V-3T144C	256	3.3	3	TQFP	144	96	C
	LC4256V-5T144C	256	3.3	5	TQFP	144	96	C
	LC4256V-75T144C	256	3.3	7.5	TQFP	144	96	C
	LC4256V-3T100C	256	3.3	3	TQFP	100	64	C
	LC4256V-5T100C	256	3.3	5	TQFP	100	64	C
	LC4256V-75T100C	256	3.3	7.5	TQFP	100	64	C
LC4384V	LC4384V-35FT256C	384	3.3	3.5	ftBGA	256	192	C
	LC4384V-5FT256C	384	3.3	5	ftBGA	256	192	C
	LC4384V-75FT256C	384	3.3	7.5	ftBGA	256	192	C
	LC4384V-35F256C ¹	384	3.3	3.5	fpBGA	256	192	C
	LC4384V-5F256C ¹	384	3.3	5	fpBGA	256	192	C
	LC4384V-75F256C ¹	384	3.3	7.5	fpBGA	256	192	C
	LC4384V-35T176C	384	3.3	3.5	TQFP	176	128	C
	LC4384V-5T176C	384	3.3	5	TQFP	176	128	C
	LC4384V-75T176C	384	3.3	7.5	TQFP	176	128	C

ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4512V	LC4512V-35FT256C	512	3.3	3.5	ftBGA	256	208	C
	LC4512V-5FT256C	512	3.3	5	ftBGA	256	208	C
	LC4512V-75FT256C	512	3.3	7.5	ftBGA	256	208	C
	LC4512V-35F256C ¹	512	3.3	3.5	fpBGA	256	208	C
	LC4512V-5F256C ¹	512	3.3	5	fpBGA	256	208	C
	LC4512V-75F256C ¹	512	3.3	7.5	fpBGA	256	208	C
	LC4512V-35T176C	512	3.3	3.5	TQFP	176	128	C
	LC4512V-5T176C	512	3.3	5	TQFP	176	128	C
	LC4512V-75T176C	512	3.3	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-5T48I	32	3.3	5	TQFP	48	32	I
	LC4032V-75T48I	32	3.3	7.5	TQFP	48	32	I
	LC4032V-10T48I	32	3.3	10	TQFP	48	32	I
	LC4032V-5T44I	32	3.3	5	TQFP	44	30	I
	LC4032V-75T44I	32	3.3	7.5	TQFP	44	30	I
	LC4032V-10T44I	32	3.3	10	TQFP	44	30	I
LC4064V	LC4064V-5T100I	64	3.3	5	TQFP	100	64	I
	LC4064V-75T100I	64	3.3	7.5	TQFP	100	64	I
	LC4064V-10T100I	64	3.3	10	TQFP	100	64	I
	LC4064V-5T48I	64	3.3	5	TQFP	48	32	I
	LC4064V-75T48I	64	3.3	7.5	TQFP	48	32	I
	LC4064V-10T48I	64	3.3	10	TQFP	48	32	I
	LC4064V-5T44I	64	3.3	5	TQFP	44	30	I
	LC4064V-75T44I	64	3.3	7.5	TQFP	44	30	I
	LC4064V-10T44I	64	3.3	10	TQFP	44	30	I
LC4128V	LC4128V-5T144I	128	3.3	5	TQFP	144	96	I
	LC4128V-75T144I	128	3.3	7.5	TQFP	144	96	I
	LC4128V-10T144I	128	3.3	10	TQFP	144	96	I
	LC4128V-5T128I	128	3.3	5	TQFP	128	92	I
	LC4128V-75T128I	128	3.3	7.5	TQFP	128	92	I
	LC4128V-10T128I	128	3.3	10	TQFP	128	92	I
	LC4128V-5T100I	128	3.3	5	TQFP	100	64	I
	LC4128V-75T100I	128	3.3	7.5	TQFP	100	64	I
	LC4128V-10T100I	128	3.3	10	TQFP	100	64	I

ispMACH 4000V (3.3V) Industrial Devices (Cont.)

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-5FT256AI	256	3.3	5	ftBGA	256	128	I
	LC4256V-75FT256AI	256	3.3	7.5	ftBGA	256	128	I
	LC4256V-10FT256AI	256	3.3	10	ftBGA	256	128	I
	LC4256V-5FT256BI	256	3.3	5	ftBGA	256	160	I
	LC4256V-75FT256BI	256	3.3	7.5	ftBGA	256	160	I
	LC4256V-10FT256BI	256	3.3	10	ftBGA	256	160	I
	LC4256V-5F256AI ¹	256	3.3	5	fpBGA	256	128	I
	LC4256V-75F256AI ¹	256	3.3	7.5	fpBGA	256	128	I
	LC4256V-10F256AI ¹	256	3.3	10	fpBGA	256	128	I
	LC4256V-5F256BI ¹	256	3.3	5	fpBGA	256	160	I
	LC4256V-75F256BI ¹	256	3.3	7.5	fpBGA	256	160	I
	LC4256V-10F256BI ¹	256	3.3	10	fpBGA	256	160	I
	LC4256V-5T176I	256	3.3	5	TQFP	176	128	I
	LC4256V-75T176I	256	3.3	7.5	TQFP	176	128	I
	LC4256V-10T176I	256	3.3	10	TQFP	176	128	I
	LC4256V-5T144I	256	3.3	5	TQFP	144	96	I
	LC4256V-75T144I	256	3.3	7.5	TQFP	144	96	I
	LC4256V-10T144I	256	3.3	10	TQFP	144	96	I
	LC4256V-5T100I	256	3.3	5	TQFP	100	64	I
	LC4256V-75T100I	256	3.3	7.5	TQFP	100	64	I
	LC4256V-10T100I	256	3.3	10	TQFP	100	64	I
LC4384V	LC4384V-5FT256I	384	3.3	5	ftBGA	256	192	I
	LC4384V-75FT256I	384	3.3	7.5	ftBGA	256	192	I
	LC4384V-10FT256I	384	3.3	10	ftBGA	256	192	I
	LC4384V-5F256I ¹	384	3.3	5	fpBGA	256	192	I
	LC4384V-75F256I ¹	384	3.3	7.5	fpBGA	256	192	I
	LC4384V-10F256I ¹	384	3.3	10	fpBGA	256	192	I
	LC4384V-5T176I	384	3.3	5	TQFP	176	128	I
	LC4384V-75T176I	384	3.3	7.5	TQFP	176	128	I
	LC4384V-10T176I	384	3.3	10	TQFP	176	128	I
LC4512V	LC4512V-5FT256I	512	3.3	5	ftBGA	256	208	I
	LC4512V-75FT256I	512	3.3	7.5	ftBGA	256	208	I
	LC4512V-10FT256I	512	3.3	10	ftBGA	256	208	I
	LC4512V-5F256I ¹	512	3.3	5	fpBGA	256	208	I
	LC4512V-75F256I ¹	512	3.3	7.5	fpBGA	256	208	I
	LC4512V-10F256I ¹	512	3.3	10	fpBGA	256	208	I
	LC4512V-5T176I	512	3.3	5	TQFP	176	128	I
	LC4512V-75T176I	512	3.3	7.5	TQFP	176	128	I
	LC4512V-10T176I	512	3.3	10	TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000B (2.5V) Lead-Free Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4384B	LC4384B-35FTN256C	384	2.5	3.5	Lead-Free ftBGA	256	192	C
	LC4384B-5FTN256C	384	2.5	5	Lead-Free ftBGA	256	192	C
	LC4384B-75FTN256C	384	2.5	7.5	Lead-Free ftBGA	256	192	C
	LC4384B-35FN256C ¹	384	2.5	3.5	Lead-Free fpBGA	256	192	C
	LC4384B-5FN256C ¹	384	2.5	5	Lead-Free fpBGA	256	192	C
	LC4384B-75FN256C ¹	384	2.5	7.5	Lead-Free fpBGA	256	192	C
	LC4384B-35TN176C	384	2.5	3.5	Lead-Free TQFP	176	128	C
	LC4384B-5TN176C	384	2.5	5	Lead-Free TQFP	176	128	C
	LC4384B-75TN176C	384	2.5	7.5	Lead-Free TQFP	176	128	C
LC4512B	LC4512B-35FTN256C	512	2.5	3.5	Lead-Free ftBGA	256	208	C
	LC4512B-5FTN256C	512	2.5	5	Lead-Free ftBGA	256	208	C
	LC4512B-75FTN256C	512	2.5	7.5	Lead-Free ftBGA	256	208	C
	LC4512B-35FN256C ¹	512	2.5	3.5	Lead-Free fpBGA	256	208	C
	LC4512B-5FN256C ¹	512	2.5	5	Lead-Free fpBGA	256	208	C
	LC4512B-75FN256C ¹	512	2.5	7.5	Lead-Free fpBGA	256	208	C
	LC4512B-35TN176C	512	2.5	3.5	Lead-Free TQFP	176	128	C
	LC4512B-5TN176C	512	2.5	5	Lead-Free TQFP	176	128	C
	LC4512B-75TN176C	512	2.5	7.5	Lead-Free TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000B (2.5V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-5TN48I	32	2.5	5	Lead-Free TQFP	48	32	I
	LC4032B-75TN48I	32	2.5	7.5	Lead-Free TQFP	48	32	I
	LC4032B-10TN48I	32	2.5	10	Lead-Free TQFP	48	32	I
	LC4032B-5TN44I	32	2.5	5	Lead-Free TQFP	44	30	I
	LC4032B-75TN44I	32	2.5	7.5	Lead-Free TQFP	44	30	I
	LC4032B-10TN44I	32	2.5	10	Lead-Free TQFP	44	30	I
LC4064B	LC4064B-5TN100I	64	2.5	5	Lead-Free TQFP	100	64	I
	LC4064B-75TN100I	64	2.5	7.5	Lead-Free TQFP	100	64	I
	LC4064B-10TN100I	64	2.5	10	Lead-Free TQFP	100	64	I
	LC4064B-5TN48I	64	2.5	5	Lead-Free TQFP	48	32	I
	LC4064B-75TN48I	64	2.5	7.5	Lead-Free TQFP	48	32	I
	LC4064B-10TN48I	64	2.5	10	Lead-Free TQFP	48	32	I
	LC4064B-5TN44I	64	2.5	5	Lead-Free TQFP	44	30	I
	LC4064B-75TN44I	64	2.5	7.5	Lead-Free TQFP	44	30	I
	LC4064B-10TN44I	64	2.5	10	Lead-Free TQFP	44	30	I